MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ODCSP16 4x4, 1.12P
CASE 570CN
ISSUE A

DATE 07 JAN 2021

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,
   2009.
2. CONTROLLING DIMENSION MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY
   THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS
   OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM
   CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. SOLDER BALLS ARE PERFECTLY ALIGNED TO THE
   CENTER OF THE SENSOR (ACTIVE AREA).

DETAIL B
Horizontal metal track on silicon connected to pad

DETAIL C
Horizontal metal track on silicon not connected to pad

DOCUMENT NUMBER:
98AON94887G

DESCRIPTION:
ODCSP16 4x4, 1.12P

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries.
ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

© Semiconductor Components Industries, LLC, 2018 www.onsemi.com